

WHAT IS CLAIMED IS:

1. A stacked semiconductor device comprising:

a plurality of semiconductor elements mounted on said device in a stacked form, each of said semiconductor elements having a quadrangular surface; and

a plurality of electrode pads provided on each of said quadrangular surfaces of said semiconductor elements, wherein

said electrode pads provided on each of said quadrangular surfaces are intensively arranged near two sides adjacent to each other, of said quadrangular surface, while

said semiconductor elements, which are adjacent to each other in a direction that said semiconductor elements are stacked, are arranged so as to be shifted in a direction parallel with said quadrangular surfaces in such a manner that said electrode pads provided on each of said semiconductor elements adjacent to each other do not overlap with the other semiconductor element when viewed from a direction orthogonal to said quadrangular surfaces.

2. A stacked semiconductor device comprising:

two semiconductor elements mounted on said device in a stacked form, each of said semiconductor elements having a quadrangular surface; and

a plurality of electrode pads provided on each of said

quadrangular surfaces of said semiconductor elements,
wherein

said electrode pads provided on each of said
quadrangular surfaces are intensively arranged near one
5 side of said quadrangular surface, while

said semiconductor elements are arranged so as to be
shifted in a direction parallel with said quadrangular
surfaces in such a manner that said quadrangular surface of
one of said semiconductor elements is faced to said
10 quadrangular surface of the other semiconductor element and
said electrode pads provided on each of said semiconductor
elements do not overlap with the other semiconductor
element when viewed from a direction orthogonal to said
quadrangular surfaces.

15 3. A stacked semiconductor device comprising:

a plurality of semiconductor elements mounted on said
device in a stacked form; and

a plurality of electrode pads provided on each of said
semiconductor elements, wherein

20 said electrode pads provided on each of said
semiconductor element are arranged on a side surface of
said semiconductor element.

4. The stacked semiconductor device according to
claim 3, wherein each of said side surfaces is slanted for
25 a horizontal surface of said semiconductor element.

5. The stacked semiconductor device according to claim 1, wherein

5 said semiconductor elements, which are adjacent to each other in the direction that said semiconductor elements are stacked, are directly joined to each other by means of an adhesive.

6. The stacked semiconductor device according to claim 2, wherein

10 said semiconductor elements are directly joined to each other by means of an adhesive.

7. The stacked semiconductor device according to claim 3, wherein

15 said semiconductor elements, which are adjacent to each other in the direction that said semiconductor elements are stacked, are directly joined to each other by means of an adhesive.

8. The stacked semiconductor device according to claim 4, wherein

20 said semiconductor elements, which are adjacent to each other in the direction that said semiconductor elements are stacked, are directly joined to each other by means of an adhesive.